



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of )  
Shinji TAKEDA et al. ) Atty. Docket No.: TM&K0007  
Serial No. 09/785,436 )  
Filed: February 20, 2001 ) Group Art Unit: 2813  
For: SEMICONDUCTOR DEVICE AND ) Examiner: Scott Geyer  
PROCESS FOR FABRICATION )  
THEREOF ) Date: January 3, 2003

AMENDMENT (E)

**BOX: Fee Amendment**  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the official Office Action dated October 4, 2002, please amend the above-captioned application as follows:

IN THE CLAIMS

Please cancel claims 29, 31, 36, 37 and 55-62 without prejudice.

IN THE SPECIFICATION

Please amend the specification as follows.

1. Please replace the paragraph on page 3, line 21 to page 4, line 1, with the following new paragraph:

El The filmy organic die-bonding material 1 is contact-bonded to a die pad 6 of a lead frame 5 on a heating platen 7 by means of a contact press 4 as shown in Fig. 1(b). The contact